

- Member of the Texas Instruments Widebus™ Family
- Operates From 2.7 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 4.2 ns at 3.3 V
- $I_{off}$  and Power-Up 3-State Support Hot Insertion
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V  $V_{CC}$ )
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

#### description/ordering information

This 16-bit buffer/driver is designed for 2.7-V to 3.6-V  $V_{CC}$  operation.

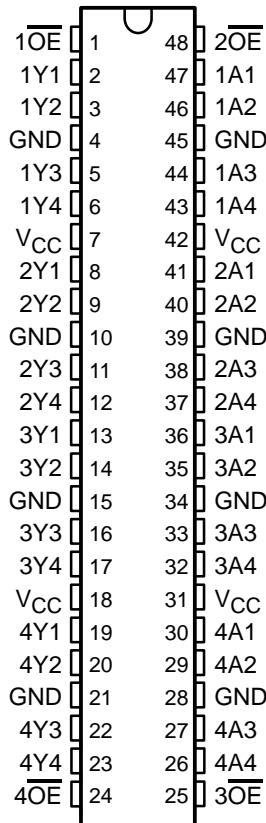
The SN74LVCZ16240A is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides inverting outputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

During power up or power down when  $V_{CC}$  is between 0 and 1.5 V, the device is in the high-impedance state. However, to ensure the high-impedance state above 1.5 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



#### ORDERING INFORMATION

$T_A$	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74LVCZ16240ADL	LVCZ16240A
		Tape and reel	SN74LVCZ16240ADLR	
	TSSOP – DGG	Tape and reel	SN74LVCZ16240ADGGR	LVCZ16240A
	TVSOP – DGV	Tape and reel	SN74LVCZ16240ADGVR	CW240A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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**SN74LVCZ16240A**  
**16-BIT BUFFER/DRIVER**  
**WITH 3-STATE OUTPUTS**

SCES276D – JUNE 1999 – REVISED AUGUST 2002

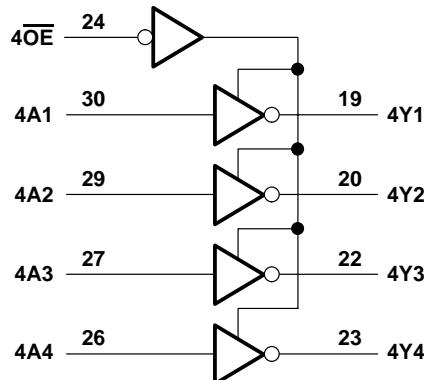
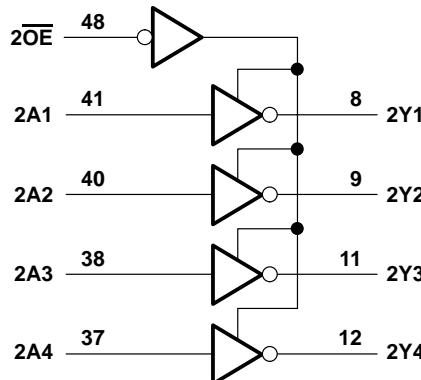
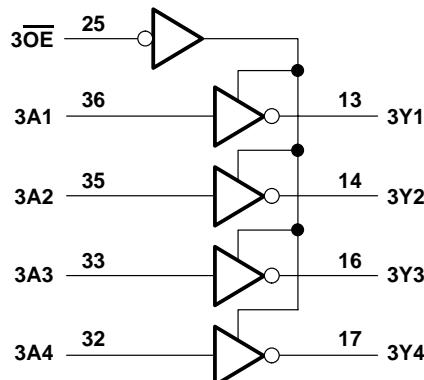
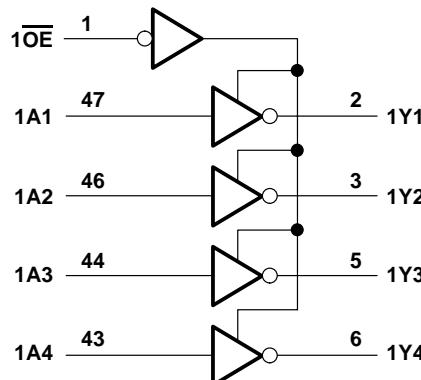
**description/ordering information (continued)**

This device is fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down ( $V_{CC} = 0$  V). The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

**FUNCTION TABLE**  
(each 4-bit buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	–0.5 V to 6.5 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1) .....	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, $V_O$ (see Notes 1 and 2) .....	–0.5 V to $V_{CC}$ + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	–50 mA
Continuous output current, $I_O$ .....	±50 mA
Continuous current through each $V_{CC}$ or GND .....	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	
DGG package .....	70°C/W
DGV package .....	58°C/W
DL package .....	63°C/W
Storage temperature range, $T_{STG}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The value of  $V_{CC}$  is provided in the recommended operating conditions table.  
3. The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions (see Note 4)**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2.7	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2.7$ V to 3.6 V	2	V
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.7$ V to 3.6 V	0.8	V
$V_I$	Input voltage	0	5.5	V
$V_O$	Output voltage	0	$V_{CC}$	V
	3-state	0	5.5	
$I_{OH}$	High-level output current	$V_{CC} = 2.7$ V	–12	mA
		$V_{CC} = 3$ V	–24	
$I_{OL}$	Low-level output current	$V_{CC} = 2.7$ V	12	mA
		$V_{CC} = 3$ V	24	
$\Delta t/\Delta V$	Input transition rise or fall rate		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	150		μs/V
$T_A$	Operating free-air temperature	–40	85	°C

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**SN74LVCZ16240A**  
**16-BIT BUFFER/DRIVER**  
**WITH 3-STATE OUTPUTS**

SCES276D – JUNE 1999 – REVISED AUGUST 2002

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 µA	2.7 V to 3.6 V	V <sub>CC</sub> -0.2			V
	I <sub>OH</sub> = -12 mA	2.7 V	2.2			
	I <sub>OH</sub> = -24 mA	3 V	2.4			
V <sub>OL</sub>	I <sub>OL</sub> = 100 µA	2.7 V to 3.6 V		0.2		V
	I <sub>OL</sub> = 12 mA	2.7 V		0.4		
	I <sub>OL</sub> = 24 mA	3 V		0.55		
I <sub>I</sub>	V <sub>I</sub> = 0 to 5.5 V	3.6 V		±5		µA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0		±5		µA
I <sub>OZ</sub>	V <sub>O</sub> = 0 to 5.5 V	3.6 V		±5		µA
I <sub>OZPU</sub>	V <sub>O</sub> = 0.5 V to 2.5 V, $\overline{OE}$ = don't care	0 to 1.5 V		±5		µA
I <sub>OZPD</sub>	V <sub>O</sub> = 0.5 V to 2.5 V, $\overline{OE}$ = don't care	1.5 V to 0		±5		µA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	I <sub>O</sub> = 0	3.6 V		100	µA
	3.6 V ≤ V <sub>I</sub> ≤ 5.5 V‡				100	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V		100		µA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		4.5		pF
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V		6		pF

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ This applies in the disabled state only.

**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
			1	4.5	1	4.2	ns
t <sub>pd</sub>	A	Y	1	4.5	1	4.2	ns
t <sub>en</sub>	$\overline{OE}$	Y	1.5	5	1.5	4.7	ns
t <sub>dis</sub>	$\overline{OE}$	Y	1.5	6.2	1.5	5.9	ns

**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
			1	4.4	1	4.1	ns
t <sub>pd</sub>	A	Y	1	4.4	1	4.1	ns
t <sub>en</sub>	$\overline{OE}$	Y	1	4.8	1	4.5	ns
t <sub>dis</sub>	$\overline{OE}$	Y	1.4	5.9	1.4	5.6	ns

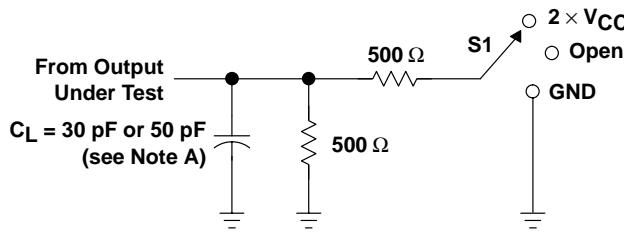
**operating characteristics, T<sub>A</sub> = 25°C**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 3.3 V		UNIT
		TYP		
C <sub>pd</sub> Power dissipation capacitance per buffer/driver	Outputs enabled	f = 10 MHz	31	pF
	Outputs disabled		3.5	



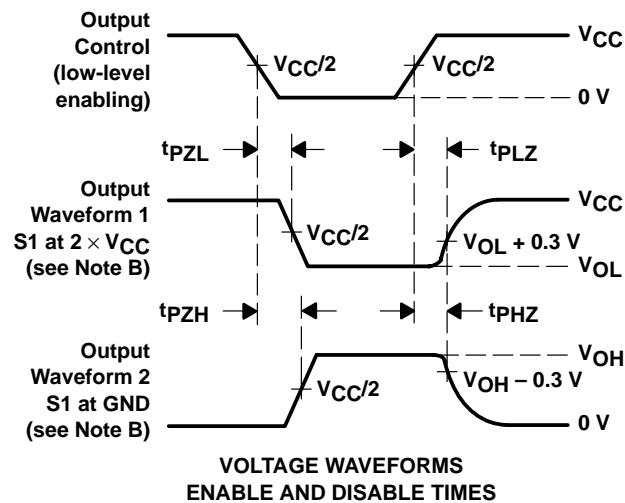
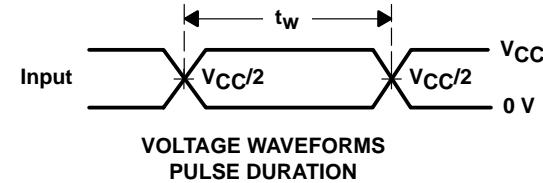
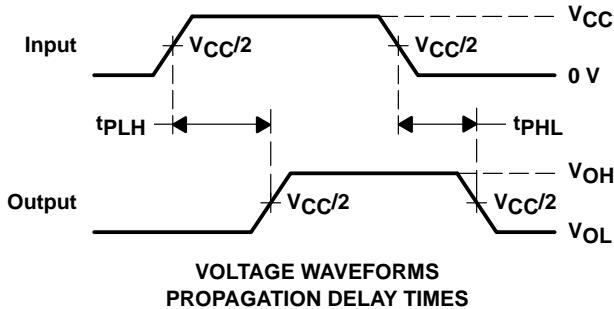
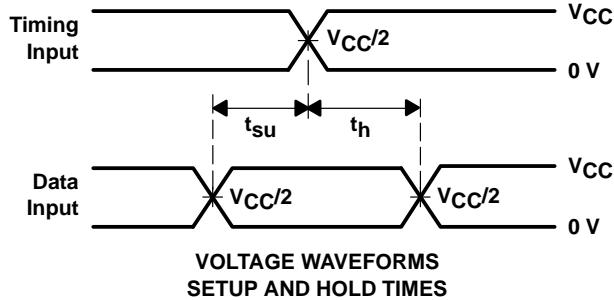
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PARAMETER MEASUREMENT INFORMATION  
 $V_{CC} = 2.7\text{ V AND }3.3\text{ V} \pm 0.3\text{ V}$



TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	2 × VCC
$t_{PHZ}/t_{PZH}$	GND

LOAD CIRCUIT



NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\text{ }\Omega$ ,  $t_f \leq 2\text{ ns}$ ,  $t_r \leq 2\text{ ns}$ .
- The outputs are measured one at a time with one transition per measurement.
- $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVCZ16240ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCZ16240A	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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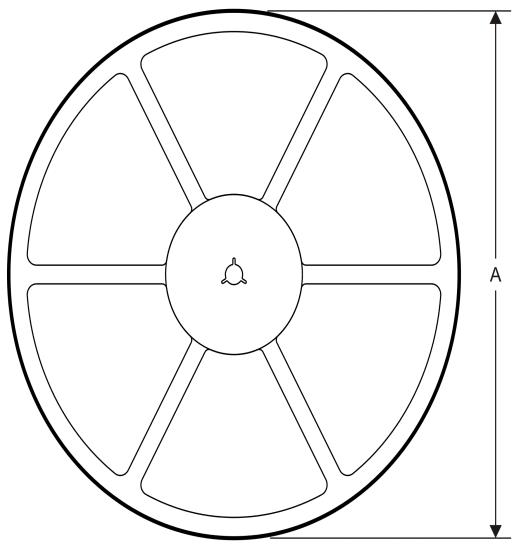
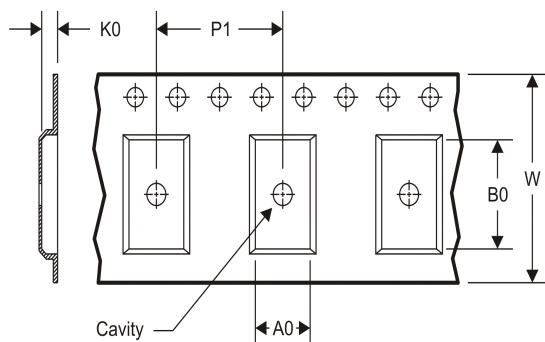


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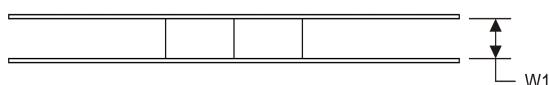
## PACKAGE OPTION ADDENDUM

10-Jun-2014

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers


**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVCZ16240ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

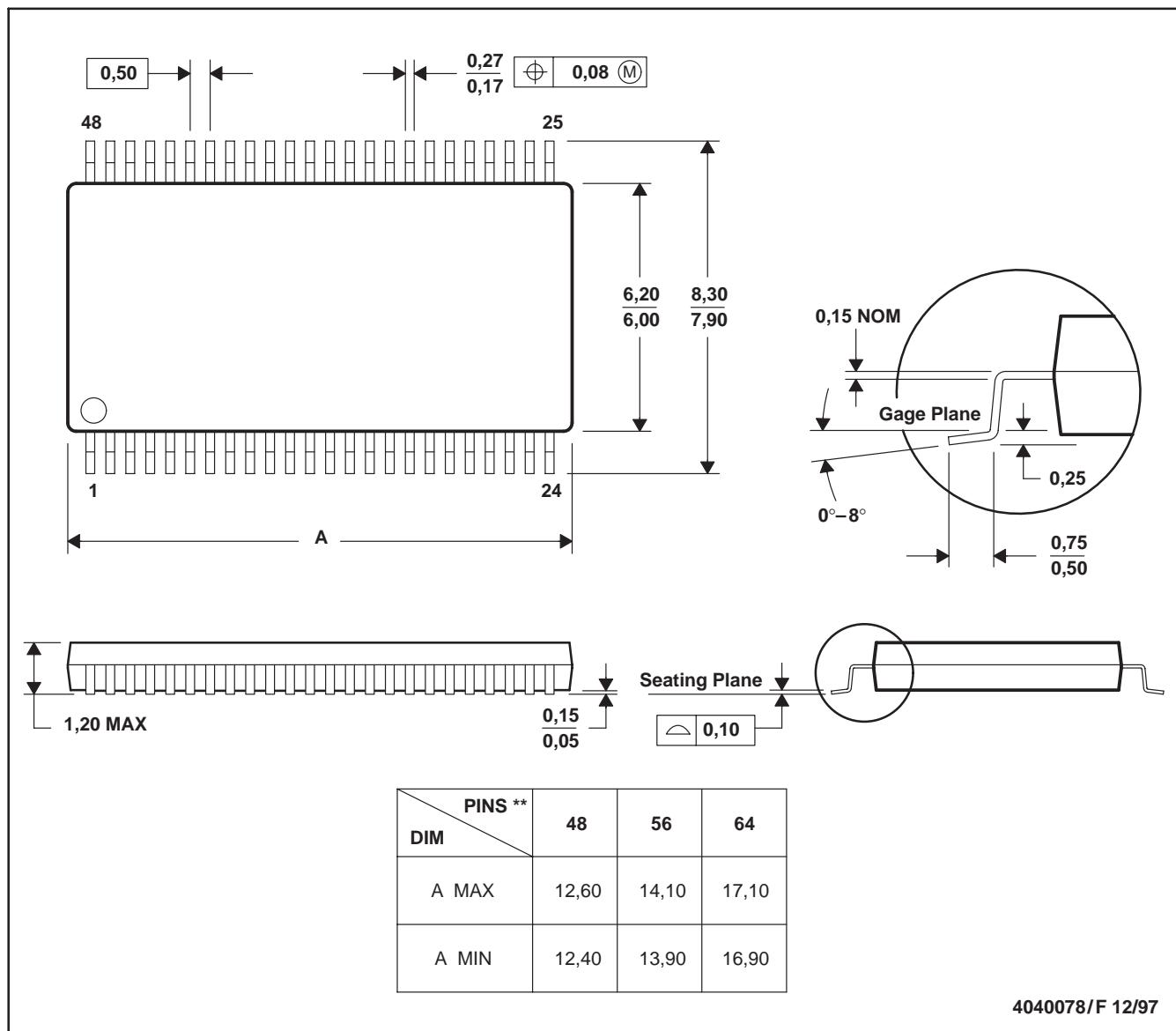
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVCZ16240ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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